T-1 (3mm) RIGHT ANGLE LED INDICATOR

Part Number: WP934EW/GD

Green

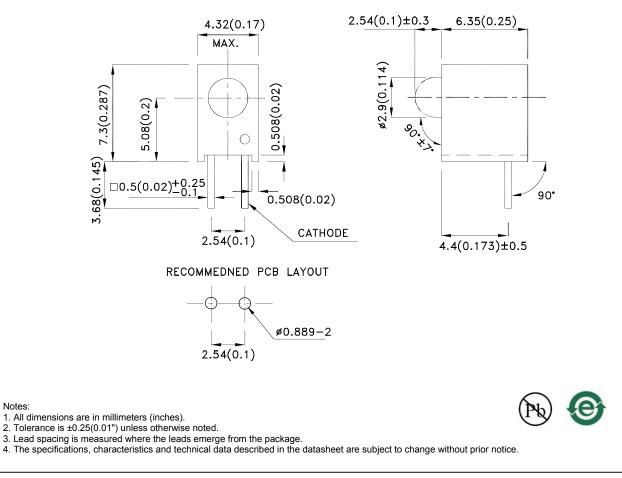
Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



SPEC NO: DSAF1855 APPROVED: WYNEC REV NO: V.7B CHECKED: Allen Liu DATE: NOV/02/2012 DRAWN: Y.H.Wu PAGE: 1 OF 5 ERP: 1102013066

Selection Guide lv (mcd) [2] Viewing @ 10mA Angle [1] Part No. Dice Lens Type Min. 201/2 Тур. WP934EW/GD Green (GaP) Green Diffused 10 25 40°

Notes:

θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Green	568		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.2	2.5	V	IF=20mA
lr	Reverse Current	Green		10	uA	VR = 5V

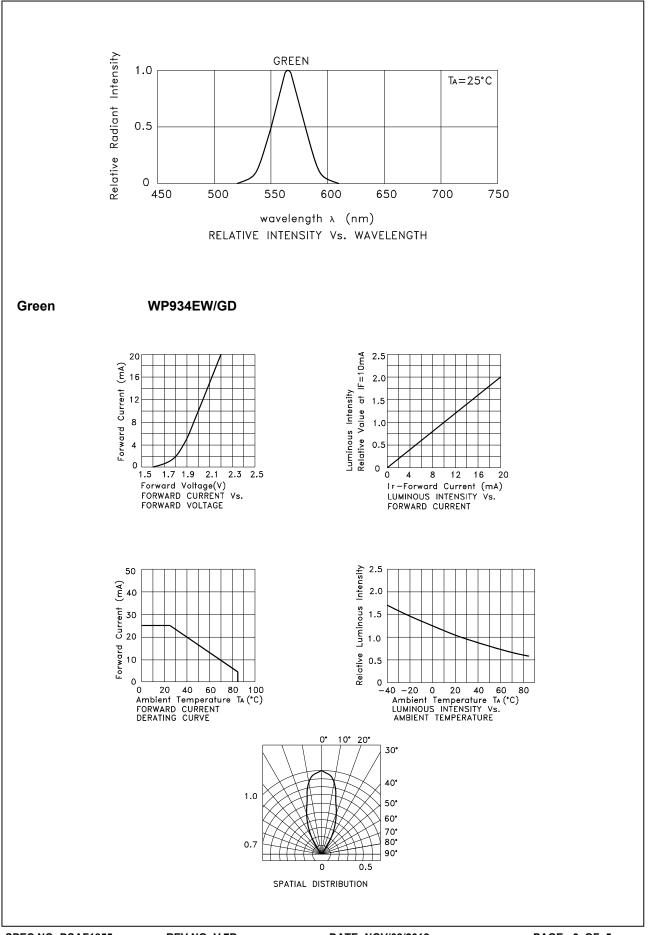
Notes: 1.Wavelength: +/-1nm. 2.Forward Voltage: +/-0.1V. 3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

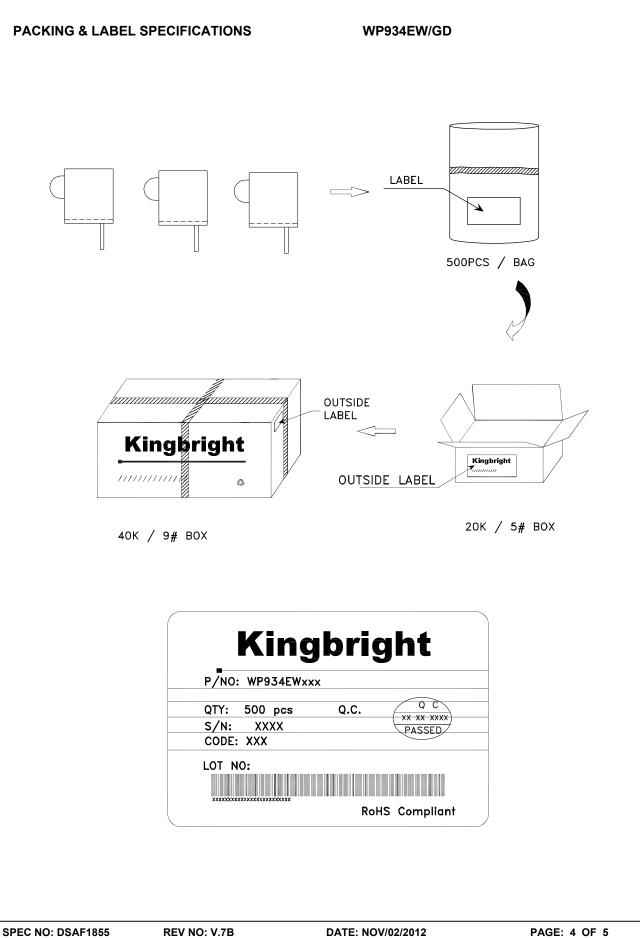
Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units			
Power dissipation	62.5	mW			
DC Forward Current	25	mA			
Peak Forward Current [1]	140	mA			
Reverse Voltage	5	V			
Operating/Storage Temperature	-40°C To +85°C				
Lead Solder Temperature [2]	260°C For 3 Seconds	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds				

Notes:

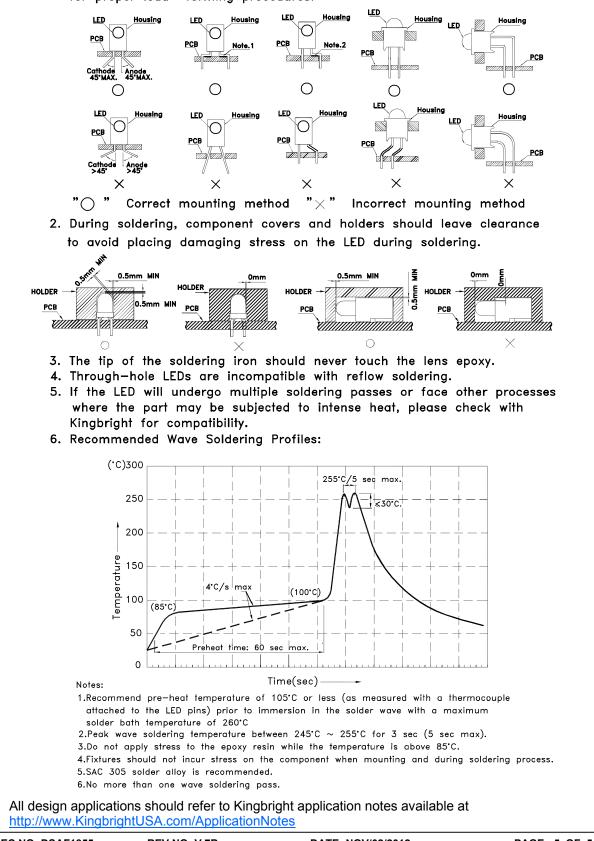
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



DATE: NOV/02/2012 DRAWN: Y.H.Wu